

- 1N6639 thru 1N6641 AVAILABLE IN JAN, JANTX, JANTXV, AND JANS PER MIL-PRF-19500/609
- SWITCHING DIODES
- NON-CAVITY GLASS PACKAGE
- METALLURGICALLY BONDED

1N6639

1N6640

1N6641

MAXIMUM RATINGS

Operating Temperature: -65°C to +175°C
 Storage Temperature: -65°C to +175°C
 Operating Current: 300 mA
 Derating: 3 mA/°C Above $T_L = +75^\circ\text{C} @ L = \frac{3}{8}"$
 Surge Current: $I_{FSM} = 2.5A, P_w = 8.3ms$

ELECTRICAL CHARACTERISTICS @ 25°C, unless otherwise specified.

TYPES	V_{BRR} @ 10 μA	V_{RWM}	I_{R1} @ $T_A = +25^\circ\text{C}$ $V_R = V_{RWM}$	I_{R2} @ $T_A = +150^\circ\text{C}$ $V_R = V_{RWM}$	T_{FR} $I_F = 200 \text{ mA}$	T_{RR}	C_T $V_R = 0$
	$V_{(PK)}$ MIN	$V_{(PK)}$	nA dc	μA dc	ns	ns	pF
1N6639	100	75	100	100	10	4.0	2.5
1N6640	75	50	100	100	10	4.0	2.5
1N6641	75	50	100	100	10	5.0	3.0

FORWARD VOLTAGE:

TYPES	V_F @ I_F		mA (PULSED)
	V dc		
	MIN	MAX	
1N6639	-	1.20	500
1N6640	0.54	0.62	1
	0.76	0.86	50
	0.82	0.92	100
	0.87	1.00	200
1N6641	-	1.10	200

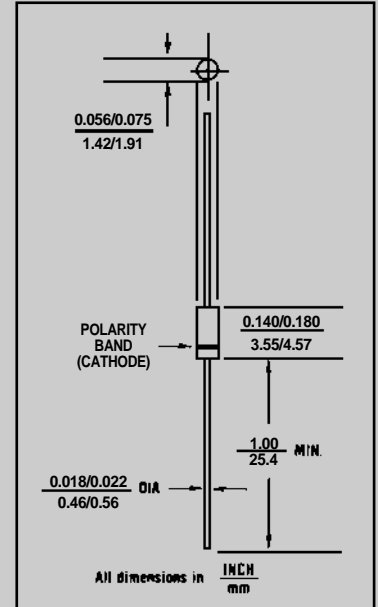


FIGURE 1

DESIGN DATA

CASE: Hermetically sealed, "D" Body per MIL-PRF- 19500/609. D-5D

LEAD MATERIAL: Copper clad steel

LEAD FINISH: Tin / Lead

THERMAL RESISTANCE: ($R_{\theta JL}$): 160 °C/W maximum at $L = .375$

THERMAL IMPEDANCE: ($Z_{\theta JX}$): 25 °C/W maximum

POLARITY: Cathode end is banded.

MOUNTING POSITION: Any



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IN6639 thru IN6641

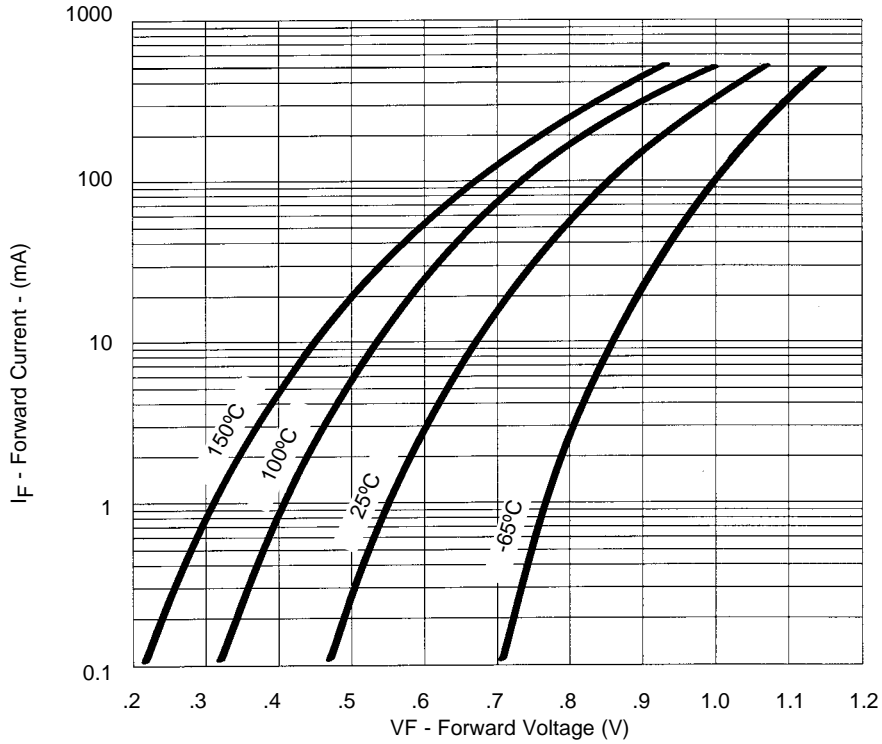


FIGURE 2
Typical Forward Current
vs Forward Voltage

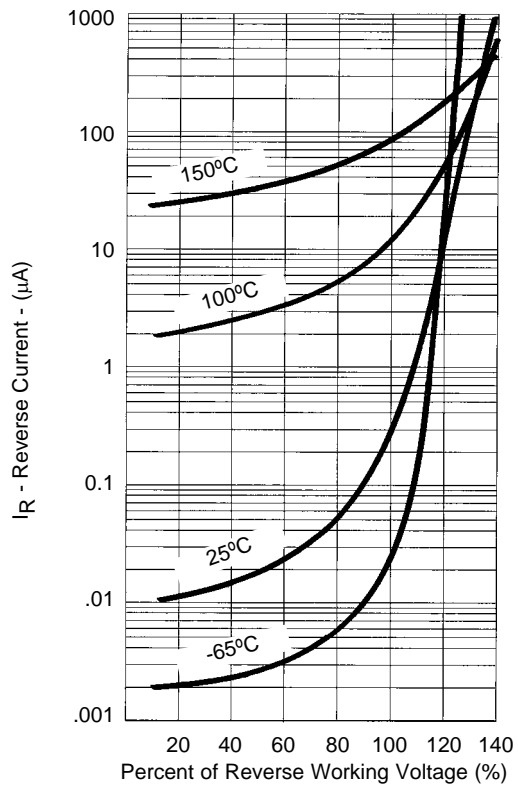


FIGURE 3
Typical Reverse Current
vs Reverse Voltage

NOTE : All temperatures shown on graphs are junction temperatures